HEUCOPHOS® ZPO

in Silicone resin

Solvent based coatings Evonik Tego formulation No. 3001 Rev. Number: 01.01 08/07

Function	Product	Producer	PBW
Silicone epoxy hybrid resin	SILIKOPON® EW	Evonik	26.30
Copper chromite black spinel	HEUCODUR® Black 9-100	Sudarshan	8.00
Carbon black pigment	PRINTEX® L	Orion Engineered Carbons	1.20
Mica/quartz/chlorite filler	Plastorit® 0000	Imerys	9.20
Magnesium silicate	Microtalc™ IT Extra	Elementis	5.10
Anticorrosive pigment	HEUCOPHOS® ZPO	Sudarshan	5.00
Solvent	Solvesso™ 100	ExxonMobil	13.00
Rheology modifier	BENTONE® SD-2	Elementis	0.20
Solvent	Methoxypropyl acetate		4.50
Grind.			
Silicone epoxy hybrid resin	SILIKOPON® EW	Evonik	15.80
Solvent	Butyl acetate		4.60
Solvent	Xylene		7.10
Add while stirring.			

100.00

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